



IR-2156 (2-2817)

2827/\$
#4
125
J. McInnis
11/13/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Mario MERLIN, et al.

Serial No.: 10/057,399

Filed: January 25, 2002

New York, New York

Date: December 24, 2002

Group Art Unit: 2827

Examiner: J. M. Mitchell

RECEIVED
JAN - 8 2003
TECHNOLOGY CENTER 2800

For: COMPRESSION ASSEMBLED ELECTRONIC PACKAGE HAVING A
PLASTIC MOLDED INSULATION RING

Assistant Commissioner for Patents
Washington, D.C. 20231

SUBMISSION

Sir:

Submitted herewith is a copy of art together with a form listing the same for the convenience of the Examiner.

I respectfully request that the information submitted be considered and enclose our check number 14633 in payment of the required \$180.00 fee.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee due during the pendency of this application is not paid, the Patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on December 26, 2002:

Kourosh Salehi
Name of applicant, assignee or
Registered Representative

Kourosh Salehi
Signature

December 26, 2002

Date of Signature

Respectfully submitted,

Kourosh Salehi
Kourosh Salehi

Registration No.: 43,898

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700

KS:ck

00595407.1

01/06/2003 MBERHE 00000016 10057399

01 FC:1806

180.00 OP